



Deep Learning and Its Applications in Image Reconstruction

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Message from the Guest Editors

Three-dimensional shape reconstruction from single or multiple images acquired using a single or multiple cameras is a classical problem in computer vision that has been approached via many techniques. Despite great progress achieved in 3D reconstruction from acquired data, accurate depth map recovery is still a big challenge. Deep learning techniques have attracted many researchers to the computer vision field to solve problems such as image segmentation, object detection, and recognition. This success has also led to the implementation of deep learning techniques for 3D reconstruction. Deep neural networks are especially suitable because they are able to encode rich prior information about the space of 3D shapes, which helps to resolve ambiguities. These models can learn a diverse type of features to ultimately allow robust 3D reconstruction.

The purpose of this Special Issue is to disseminate original research papers or state-of-the-art surveys that pertain to novel or emerging techniques and applications in the field of computer vision.





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Message from the Editor-in-Chief

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